

MMIC Silicon Bipolar Broadband Amplifier

The ISL55005, ISL55007, ISL55008 and ISL55009, ISL55010, ISL55011 constitute a family of high performance gain blocks featuring a Darlington configuration using high f_t transistors and excellent thermal performance. They are an ideal choice for DVB-S LNB cable receiver applications.

ISL55005, ISL55007, ISL55008 offer higher OIP3 performance while the ISL55009, ISL55010, ISL55011 offer lower operating supply currents.

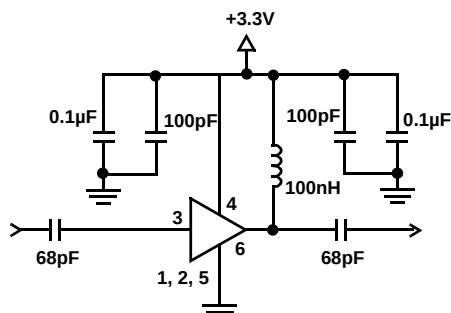
ISL55005 and ISL55009 match a 75Ω source to a 50Ω load. ISL55007 and ISL55010 match a 75Ω source to a 75Ω load. ISL55008 and ISL55011 match a 50Ω source to a 50Ω load.

Ordering Information

PART NUMBER (Note)	PART MARKING	TAPE & REEL	PACKAGE (Pb-Free)	PKG. DWG. #
ISL55005IEZ-T7	CSA	7" (3k pcs)	6 Ld SC-70	P6.049

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Typical Application Circuit



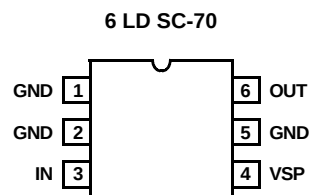
Features

- Input impedance of 75Ω
- Output impedance of 50Ω
- Noise figure of 3.6dB
- OIP3 of 17dBm
- Low input and output return losses
- Pb-free plus anneal available (RoHS compliant)

Applications

- LNB and LNB-T line amplifiers
- IF gain blocks for satellite and terrestrial HDTV STBs
- PA driver amplifier
- Wireless data, satellite
- Bluetooth/WiFi
- Satellite locator and signal strength meters

Pinout



Absolute Maximum Ratings (T_A = 25°C)

Supply Voltage from VSP to GND 6V
 Input Voltage V_S + 0.3V to GND -0.3V
 Power Dissipation See Packaging Information Section
 Ambient Operating Temperature -40°C to +85°C

Storage Temperature -65°C to +125°C
 Operating Junction Temperature +125°C
 ESD Rating
 Human Body Model (Per MIL-STD-883 Method 3015.7) ... 3000V
 Machine Model (Per EIAJ ED-4701 Method C-111) ... 300V

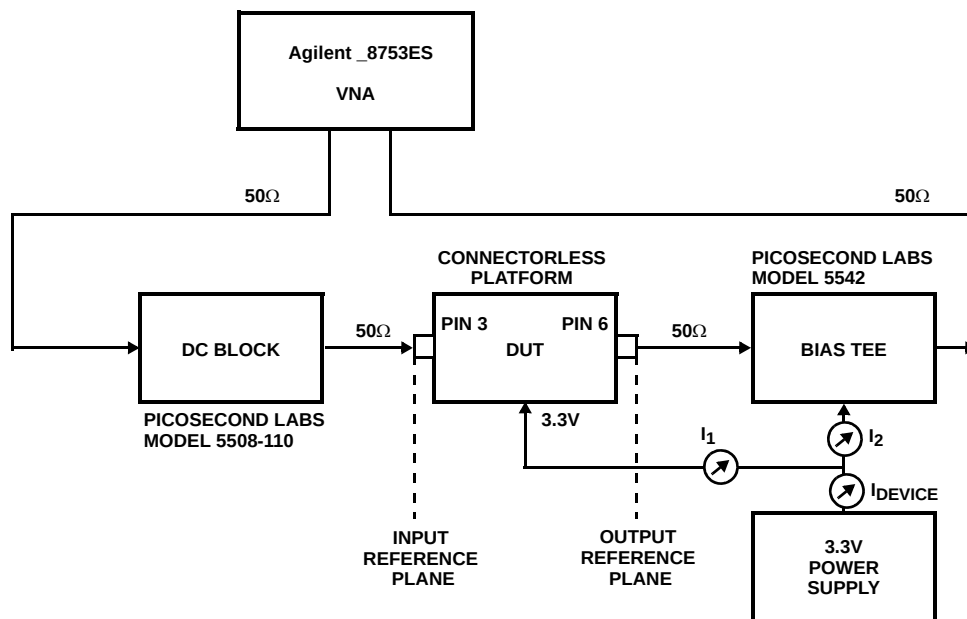
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: T_J = T_C = T_A

Electrical Specifications VSP = +3.3V, Z_{src} = Z_{load} = 50Ω, T_A = 25°C, unless otherwise specified.

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
Gt	Small Signal Gain	1.0GHz	16.2	17.2	18.2	dB
		1.5GHz	16.0	17.0	18.0	dB
		2.0GHz	15.6	16.6	17.6	dB
P1dB	Output Power at 1dB Compression	1.0GHz	5.5	7.5	9.5	dBm
		2.0GHz	4.9	6.4	7.9	dBm
OIP3	Output Third Order Intercept Point	1.0GHz		18.0		dBm
		2.0GHz		17.3		dBm
BW	3dB Bandwidth	3dB below Gain @ 500MHz		3.0		GHz
IRL	Input Return Loss	1.0GHz Z _{src} = 75Ω, Z _{load} = 50Ω		14.5		dB
ORL	Output Return Loss	1.0GHz Z _{src} = 75Ω, Z _{load} = 50Ω		17.6		dB
RISOL	Reverse Isolation	2.0GHz		21.8		dB
NF	Noise Figure	2.0GHz		3.6		dB
ID	Device Operating Current		17.5	20.6	23.5	mA

Device Test Setup



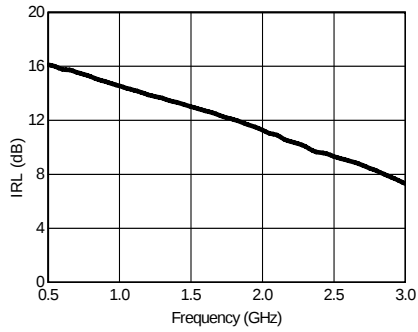
Typical Performance Curves $Z_{src} = 75\Omega$, $Z_{load} = 50\Omega$


FIGURE 1. INPUT RETURN LOSS vs FREQUENCY

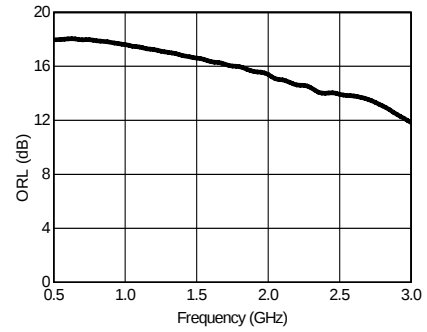


FIGURE 2. OUTPUT RETURN LOSS vs FREQUENCY

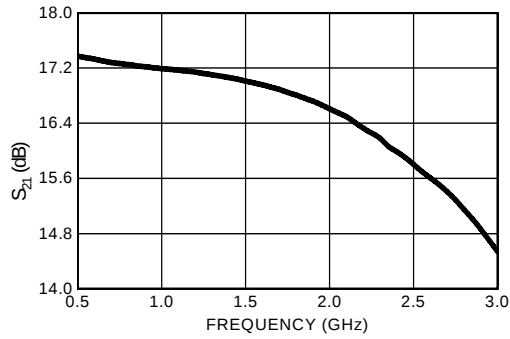
Typical Performance Curves 50 Ω environment


FIGURE 3. |S21| vs FREQUENCY

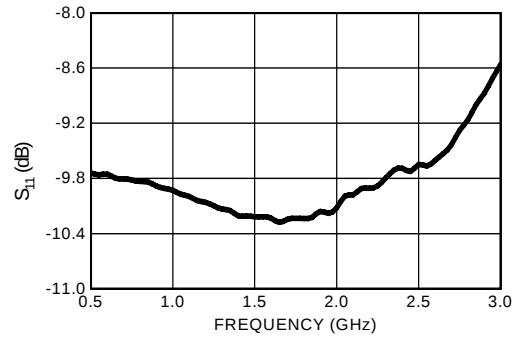


FIGURE 4. |S11| vs FREQUENCY

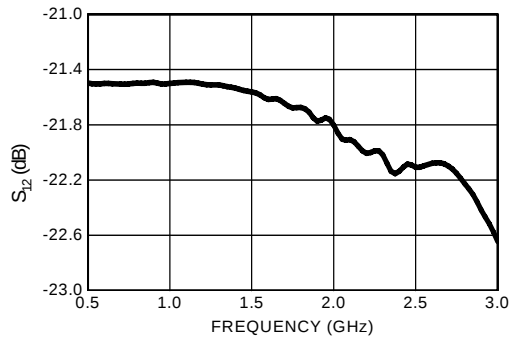


FIGURE 5. |S12| vs FREQUENCY

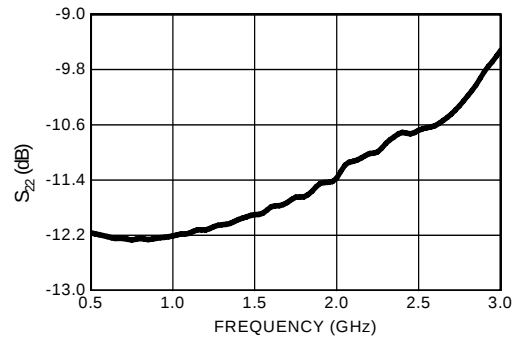


FIGURE 6. |S22| vs FREQUENCY

Typical Performance Curves 50Ω environment (Continued)

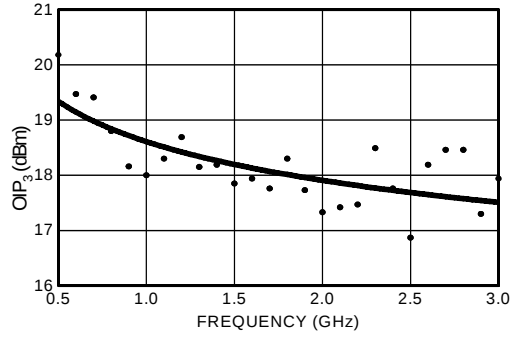


FIGURE 7. OIP3 vs FREQUENCY

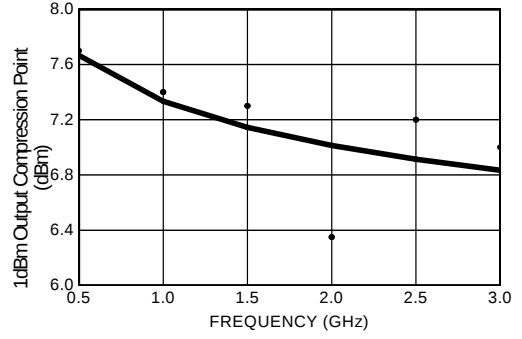


FIGURE 8. P1dB vs FREQUENCY

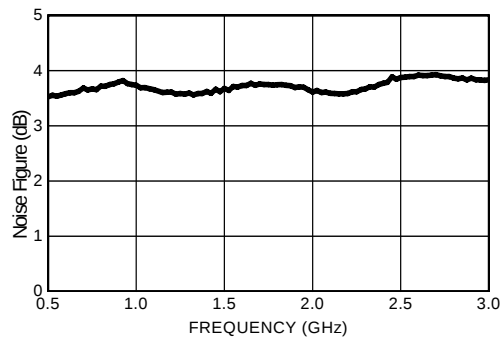


FIGURE 9. NOISE FIGURE vs FREQUENCY

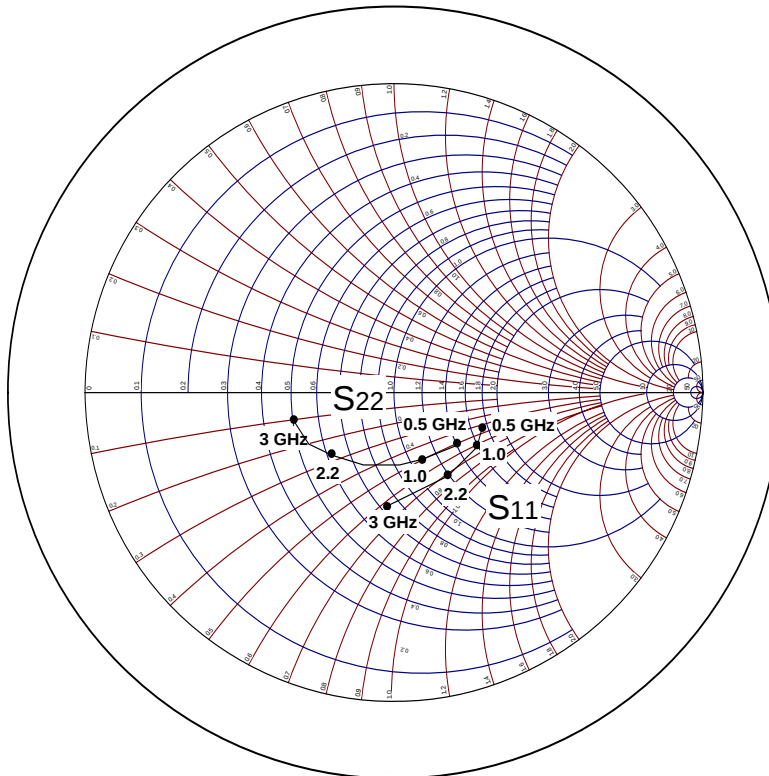


FIGURE 10. S11 AND S22 vs FREQUENCY

Packaging Information

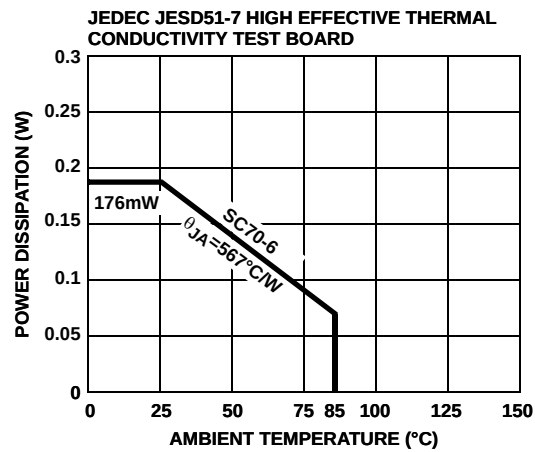


FIGURE 11. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

